



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPB120N10S4-03	Issued	10. May 2021
MA#	MA001606742		
Package	PG-TO263-3-2	Weight*	1564.83 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	8.566	0.55	0.55	5474	5474
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		58	
	non noble metal	iron	7439-89-6	0.304	0.02		195	
	non noble metal	copper	7440-50-8	304.026	19.43	19.46	194288	194541
wire	non noble metal	aluminium	7429-90-5	12.102	0.77	0.77	7734	7734
encapsulation	inorganic material	zinc oxide	1314-13-2	6.756	0.43		4318	
	miscellaneous	miscellaneous	-	27.025	1.73		17270	
	plastics	epoxy resin	-	101.344	6.48		64764	
	inorganic material	silicon dioxide	60676-86-0	540.500	34.54	43.18	345406	431758
lead finish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6171	6171
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	146	147
solder	non noble metal	tin	7440-31-5	0.117	0.01		75	
	noble metal	silver	7440-22-4	0.146	0.01		93	
	non noble metal	lead	7439-92-1	5.583	0.36	0.38	3568	3736
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		105	
	non noble metal	iron	7439-89-6	0.548	0.04		350	
	non noble metal	copper	7440-50-8	547.666	34.98	35.03	349984	350439
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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